



Material Content Data Sheet



Sales Product Name				BSZ100N06LS3 G		Issued		25. January 2018	
MA#				MA001042384					
Package				PG-TSDSON-8-2		Weight*		38.38 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.296	3.38	3.38	33767	33767	
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		55		
	non noble metal	zinc	7440-66-6	0.008	0.02		218		
	non noble metal	iron	7439-89-6	0.168	0.44		4368		
wire	non noble metal	copper	7440-50-8	6.808	17.74	18.21	177372	182013	
	non noble metal	copper	7440-50-8	0.036	0.09	0.09	931	931	
	encapsulation	organic material	carbon black	1333-86-4	0.035	0.09		905	
	plastics	epoxy resin	-	1.788	4.66		46597		
	inorganic material	silicondioxide	60676-86-0	15.540	40.49	45.24	404897	452399	
leadfinish	non noble metal	tin	7440-31-5	0.387	1.01	1.01	10087	10087	
plating	noble metal	silver	7440-22-4	0.963	2.51	2.51	25080	25080	
solder	noble metal	silver	7440-22-4	0.037	0.10		957		
	non noble metal	tin	7440-31-5	0.029	0.08		766		
	non noble metal	lead	7439-92-1	1.404	3.66	3.84	36571	38294	
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		28		
	non noble metal	zinc	7440-66-6	0.004	0.01		112		
	non noble metal	iron	7439-89-6	0.086	0.22		2247		
heat sink CLIP	non noble metal	copper	7440-50-8	3.501	9.12	9.35	91222	93609	
	inorganic material	phosphorus	7723-14-0	0.002	0.00		49		
	non noble metal	zinc	7440-66-6	0.008	0.02		197		
	non noble metal	iron	7439-89-6	0.151	0.39		3932		
	non noble metal	copper	7440-50-8	6.127	15.96	16.37	159642	163820	
*deviation	< 10%		Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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